

## TO-220AB Plastic-Encapsulate MOSFETS

### IRF730 MOSFET( N-Channel )

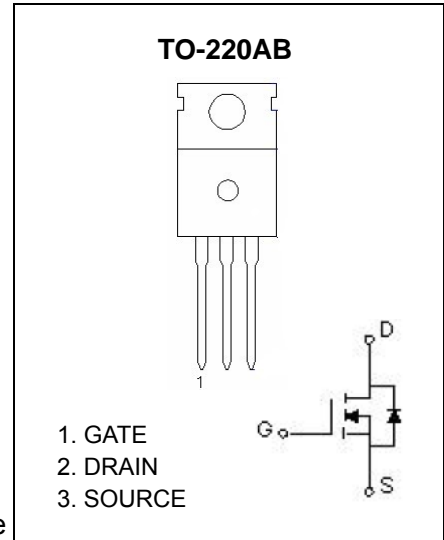
#### FEATURES

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirement

#### Description

Third Generation HEXFETs from international Rectifier provide the designer with the best combination of fast switching ,ruggedized device design,low on-resistance and cost effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



#### MAXIMUM RATINGS( $T_a=25^{\circ}\text{C}$ unless otherwise noted )

Symbol	Parameter	Value	Units
$I_D$	Continuous Drain Current, $V_{GS}$ @ 10 V $T_C=25^{\circ}\text{C}$	5.5	A
		$T_C=100^{\circ}\text{C}$	3.5
$I_{DM}$	Pulsed Drain Current (note 1 )	22	A
$P_D$	Power Dissipation	2	W
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy (note 2 )	290	mJ
$I_{AR}$	Avalanche Current (note 1 )	5.5	A
$E_{AR}$	Repetitive Avalanche Energy (note 1 )	7.4	mJ
dv/dt	Peak Diode Recovery dv/dt (note 3 )	4.0	V/ns
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	62.5	$^{\circ}\text{C}/\text{W}$
$T_J$	Junction Temperature	150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature	-55~+150	$^{\circ}\text{C}$

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25°C unless otherwise specified)**

Parameter	Symbol	Test Wnditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	400			V
Gate-threshold voltage	V <sub>(GS)th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2		4	
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =400V, V <sub>GS</sub> =0V			25	μA
		V <sub>DS</sub> =320V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C			250	
Drain-source on-resistance (note 4 )	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.3A			1.0	Ω
Forward transconductance (note 4 )	g <sub>fs</sub>	V <sub>DS</sub> =50V, I <sub>D</sub> =3.3A	2.9			S
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =5.5A, V <sub>GS</sub> =0V			1.6	V
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =320V, V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A			38	nC
Gate-source charge	Q <sub>gs</sub>				5.7	
Gate-drain charge	Q <sub>gd</sub>				22	
Input capacitance (note 5 )	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		700		pF
Output capacitance (note 5 )	C <sub>oss</sub>			170		
Reverse transfer capacitance (note 5 )	C <sub>rss</sub>			64		
Turn-on time(note 4 ,5)	t <sub>d(on)</sub>	V <sub>DD</sub> =200V, R <sub>D</sub> =57Ω, I <sub>D</sub> =3.5A, R <sub>G</sub> =12Ω		10		ns
Rise tme(note 4,5 )	t <sub>r</sub>			15		
Turn-off tme(note 4,5 )	t <sub>d(off)</sub>			38		
Fall time(note 4 ,5)	t <sub>f</sub>			14		

Notes:

1. Repetitive Rating ;Pulse width limited by maximum junction temperature.
2. L=16mH, I<sub>AS</sub> =5.5A, V<sub>DD</sub>=50V, R<sub>G</sub>=25Ω, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub>≤5.5A, di/dt≤90A/μs, V<sub>DD</sub>≤V<sub>(BR)DSS</sub>, T<sub>J</sub>≤150°C.
4. Pulse width≤300μs, Duty cycle≤2%.
5. These parameters have no way to verify.